

AMENDMENTS TO THE SPECIFICATION

Please replace the paragraph bridging page 26, line 16, to page 27, line 8, with the following amended paragraph:

As shown in FIGS. ~~FIGS.~~ 2(A) and 2(B), the COF film carrier tape 20 according to the present embodiment is formed from a laminate film 10 for producing a COF, the laminate film comprising a conductor layer 11 (copper foil) and an insulating layer 12 (polyimide film). The COF film carrier tape 20 has wiring patterns 21 obtained by patterning the conductor layer 11, and a pair of transversely spaced rows of sprocket holes 22 provided along opposite longitudinal edges of the tape. The wiring patterns 21 are provided on a surface of the insulating layer 12 continuously in the longitudinal direction of the film carrier tape. Each wiring pattern 21 has, on a surface thereof, a solder resist layer 23 which is formed by applying a solder resist coating solution through screen printing. Meanwhile, a wiring ~~pattern~~ pattern may be provided on each surface of the insulating layer (i.e., 2-metal COF film carrier tape). In this case, a releasing agent may be applied or a transferable releasing layer may be transferred exclusively to a region where a heating tool is to be in contact, to thereby form a releasing layer.

Please replace the paragraph bridging page 31, line 21, to page 32, line 9, with the following amended paragraph:

In the embodiment described above, the releasing layer 13 was formed before formation of sprocket holes 22. However, the timing of forming the releasing layer is not limited. For example, the releasing layer 13 may be formed before patterning of the conductor layer ~~12~~ 11 of the COF laminate film 10, or after removal of the resist pattern 32 with an alkali solution or a similar material and before provision of the solder resist layer 23. Alternatively, the releasing

layer 13 may be formed in the final production step after provision of the solder resist layer 23. When the releasing layer 13 is formed through the latter method, exposure of the releasing layer 13 to an etchant, a photoresist remover, etc. is prevented, thereby attaining a high releasing effect. As described hereinabove, the term "final production step" refers to as a step immediately before the product inspection step.